

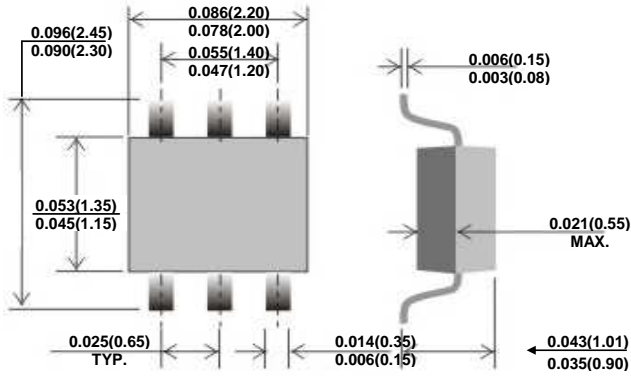


BAT54TW / ADW / CDW / SDW / DW

SURFACE MOUNT SCHOTTKY DIODES

Reverse Voltage - 30 Volts Forward Current - 0.2 Ampere

SOT-363



Dimensions in inches and (millimeters)

FEATURES

- ◆ Isolated diode arrays for significant board space savings
- ◆ Surface mount package Ideally suited for automatic insertion
- ◆ Extremely Fast Switching Speed
- ◆ Very Low VF: 0.347V (Typ) at IF = 10mA
- ◆ Lead free in comply with EU RoHS 2002/95/EC directives.

MECHANICAL DATA

Case: JEDEC SOT-363, Molded plastic

Terminals: Solderable per MIL-STD-750 · Method 2026

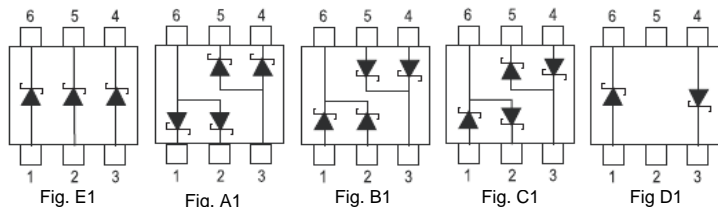
Approx. Weight: 0.0002 ounce, 0.006 gram

ABSOLUTE RATINGS AND ELECTRICAL CHARACTERISTICS (each diode)

Ratings at 25°C ambient temperature unless otherwise specified. For capacitive load, derate current by 20%.

PARAMETER	SYMBOLS	BAT54TW	BAT54ADW	BAT54CDW	BAT54SDW	BAT54DW	UNITS	
Marking Code	—	L4	L42	L43	L44	L41	—	
Forward Power Dissipation <small>(note1)</small>	P_d	225						mW
Maximum Reverse Voltage	V_R	30						Volts
Peak Reverse Voltage	V_{RRM}	30						Volts
Minimum Reverse Breakdown Voltage	$V_{(BR)}$	30						Volts
Continuous Forward Current	I_F	0.2						Amps
Maximum Forward Voltage	V_F	at $I_F = 0.1mA$ 0.24 at $I_F = 1.0mA$ 0.32 at $I_F = 10mA$ 0.40 at $I_F = 30mA$ 0.50 at $I_F = 100mA$ 1.00					Volts	
Maximum Reverse Current	I_R	2.0						μA
Maximum Total Capacitance	C_T	10						pF
Typical Thermal Resistance Junction to Ambient <small>(note1)</small>	$R_{\theta JA}$	550						$^{\circ}C/W$
Typical Thermal Resistance Junction to Lead	$R_{\theta JL}$	220						$^{\circ}C/W$
Junction Temperature Range	T_J	-55 ~ +125						$^{\circ}C$
Storage Temperature Range	T_{STG}	-55 ~ +150						$^{\circ}C$
Circuit Figure	—	Fig. E1	Fig. A1	Fig. B1	Fig. C1	Fig. D1	—	

Note: 1. FR-4 Board Minimum pad.





BAT54TW / ADW / CDW / SDW / DW

RATINGS AND CHARACTERISTIC CURVES

FIG. 1- Typical Reverse Leakage CHARACTERISTICS

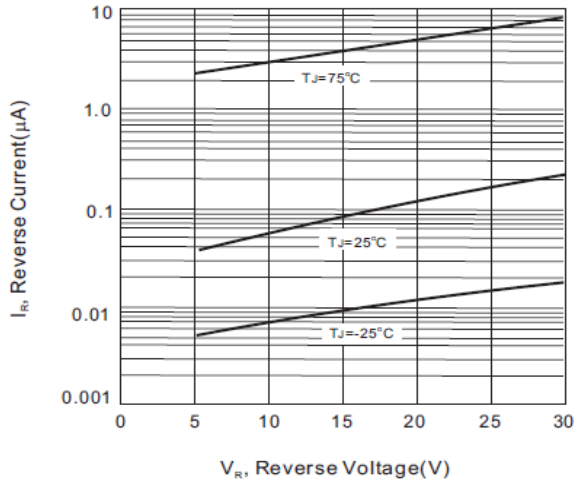


FIG. 2-TYPICAL Forward CHARACTERISTICS

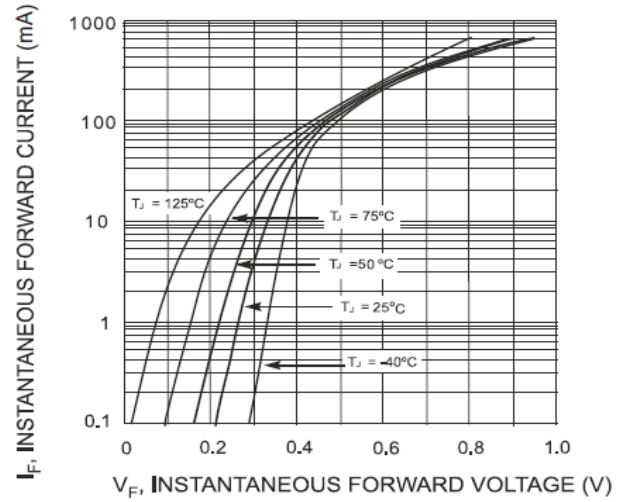


FIG. 3-TYPICAL TOTAL CAPACITANCE

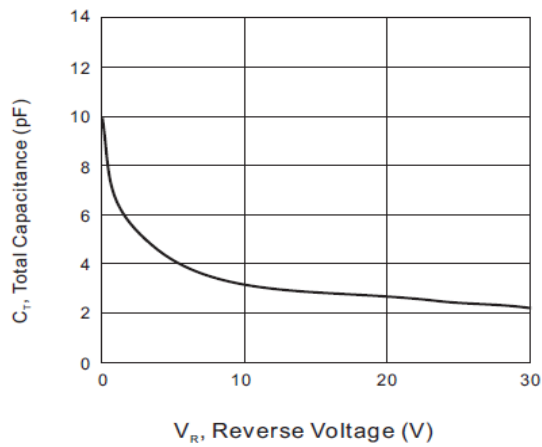


FIG. 4-MOUNTING PAD LAYOUT

